	1			
L Number	Hits	Search Text	DB	Time stamp
-	4	(("5388945") or ("5954997") or ("5770521") or ("4469777")).PN.	USPAT;	2002/08/16
_	3	(("6103625") or ("6046108") or	US-PGPUB USPAT;	15:20 2002/08/16
_	752	("6110648")) PN. or (2002/0037642).CCLS. 414/217.ccls.	US-PGPUB USPAT;	15:26 2002/08/16
			US-PGPUB	15:26
-	9 	414/217.ccls. and (PCB or (printed adj circuit adj board))	USPAT; US-PGPUB	2002/08/16 15:34
_	12	414/\$.ccls. and (PCB or (printed ad)	USPAT;	2002/08/16
		circuit adj board)) and component and dry and gas	US-PGPUB	15:52
_	1	5388945.pn.	USPAT; US-PGPUB	2002/08/16 15:40
_	11	("4724874" "4758127" "4776745"	USPAT	2002/08/16
		"4923352" "4964776" "4995430" "5059079" "5064337" "5137063"		15:40
	2.5	"5220548" "5284412").PN.		
_	25	5388945.URPN.	USPAT	2002/08/16 15:47
-	1075	(assembling with (PCB or (printed adj	USPAT;	2002/08/16
-	76	circuit adj board))) (assembling with (PCB or (printed adj	US-PGPUB USPAT;	15:59 2002/08/16
_	3	circuit adj board))) and dry (assembling with (PCB or (printed adj	US-PGPUB	16:00
		circuit adj board))) and ((dry or hot)	USPAT; US-PGPUB	2002/08/16 16:03
_	276	adj gas) (assembling with component with (PCB or	USPAT;	2002/08/16
!	2994	(printed adj circuit adj board)))	US-PGPUB	16:04
	2994	((placing or mounting or installing or assembling) with component with (PCB or	USPAT; US-PGPUB	2002/08/16 16:05
_	1806	(printed adj circuit adj board))) ((placing or mounting or installing or	USPAT;	2002/08/16
	1000	assembling) with component with (PCB or	US-PGPUB	16:06
		<pre>(printed adj circuit adj board))) and (machine or apparatus)</pre>		
_	36	((placing or mounting or installing or	USPAT;	2002/08/16
		assembling) with component with (PCB or (printed adj circuit adj board))) and	US-PGPUB	16:08
		<pre>(machine or apparatus) and ((dry or hot) with (gas or ventilation or exhhaust))</pre>		
_	66	((placing or mounting or installing or	USPAT;	2002/08/16
		assembling) with (chip or component or IC) with (PCB or (printed adj circuit adj	US-PGPUB	16:09
		board))) and (machine or apparatus) and		
		((dry or hot) with (gas or ventilation or exhhaust))		
_	17	((placing or mounting or installing or assembling) with (chip or component or	USPAT; US-PGPUB	2002/08/16 16:12
		IC) with (PCB or (printed adj circuit adj	33 10100	
		board))) and (machine or apparatus) and ((dry or hot) with (gas or ventilation or		
_	7	exhhaust)) and (storage or stock)	IICDAM -	2002/09/16
	′	mounting or installing or assembling)	USPAT; US-PGPUB	2002/08/16 16:16
		<pre>with (chip or component or IC) with (PCB or (printed adj circuit adj board))) and</pre>		
		((dry or hot) with (gas or ventilation or		
-	613	exhhaust)) and (storage or stock) ((machine or apparatus) with (placing or	USPAT;	2002/08/16
		mounting or installing or assembling) with (chip or component or IC) with (PCB	US-PGPUB	16:17
		or (printed adj circuit adj board)))		
-	23	((machine or apparatus) with (placing or mounting or installing or assembling)	USPAT; US-PGPUB	2002/08/16 16:43
		with (chip or component or IC) with (PCB	13 10100	
		or (printed adj circuit adj board))) and ((dry or hot) with (gas or ventilation or		
		exhhaust))		

_	8	("4514858" "4899921" "5235407" "5396334" "5420691" "5457538"	USPAT	2002/08/16 16:22
-	8	"5519496" "5541834").PN. 5903662.URPN.	USPAT	2002/08/16
-	200	((device or equipment or machine or apparatus or method or process) with (feeding or plac\$3 or mount\$3 or	USPAT; US-PGPUB	16:23 2002/08/16 16:51
-	49	install\$3 or assembl\$3 or insert\$3 or put\$4) with (chip or component or IC) with (PCB or (circuit adj board))) and ((dry or hot) with (gas or ventilation or exhhaust)) ((device or equipment or machine or apparatus or method or process) with (feeding or plac\$3 or mount\$3 or	USPAT; US-PGPUB	2002/08/16 16:55
		<pre>install\$3 or assembl\$3 or insert\$3 or put\$4) with (chip or component or IC) with (PCB or (circuit adj board))) and ((dry or hot) with (gas or ventilation or exhhaust)) and (moisture or humidity)</pre>		
-	4	(("6059170") or ("6284996") or ("5903662") or ("6246789")).PN.	USPAT; US-PGPUB	2002/08/19 09:21
_	2	(("5388945") or ("5884392")).PN.	USPAT; US-PGPUB USPAT;	2002/08/19 09:21 2002/08/19
_	10	("1848859" "3603528" "3798657"	US-PGPUB	12:06
		"3920394" "4513862" "5014929" "5038934" "5046674" "5123608" "5195689").PN.	USPAT	2002/08/19
-	2	5364045.URPN.	USPAT	2002/08/19
-	179	242/588.6.ccls.	USPAT; US-PGPUB	2002/08/19 12:11
-	30	242/588.6.ccls. and component	USPAT; US-PGPUB	2002/08/19
-	1051	(29/739-742).ccls. and component	USPAT; US-PGPUB	2002/08/19
-	786	(29/739-742).ccls. and component and (pcb or (circuit adj board))	USPAT; US-PGPUB	2002/08/19 12:16
-	13	or (circuit adj board)) and dry	USPAT; US-PGPUB	2002/08/19 12:20
_	2	(29/760).ccls. and component and (pcb or (circuit adj board)) and dry	USPAT; US-PGPUB	2002/08/19
_	52	(29/832).ccls. and component and (pcb or (circuit adj board)) and dry	USPAT; US-PGPUB	2002/08/19 12:46
_	0	(29/829+).ccls. and component and (pcb or (circuit adj board)) and dry 5364045.pn.	USPAT; US-PGPUB	2002/08/19
_	66	((dispensing or placing or mounting or	USPAT;	2002/08/19 12:58 2002/08/19
	30	installing or assembling) with (chip or component or IC or (surface adj mount adj device)) with (PCB or (printed adj circuit adj board))) and (machine or apparatus) and ((dry or hot) with (gas or	US-PGPUB	13:05
_	0	ventilation or exhhaust)) (pick adj place adj (component or device or machine)) and (moisture or humidity) and (dry adj (gas or atmosphere)) and	USPAT; US-PGPUB	2002/08/20 09:15
_	541	(PCB or (circuit adj board)) (pick adj place adj (component or device	USPAT;	2002/08/20
_	39	or machine)) (pick adj place adj (component or device	US-PGPUB USPAT;	09:16 2002/08/20
-	0	or machine)) and (moisture or humidity) (pick adj place adj (component or device	US-PGPUB USPAT;	09:17 2002/08/20
		or machine)) and (moisture or humidity) and (dry adj (gas or atmosphere))	US-PGPUB	09:18

-	9	<pre>(pick adj place adj (component or device or machine)) and (moisture or humidity)</pre>	USPAT; US-PGPUB	2002/08/20
		and (PCB or (circuit adj board)) and	05-PGP0B	09:20
_	0	(dry) (pick adj place adj (component or device	IICDAM.	2002/00/20
		or machine)) and (moisture or humidity)	USPAT; US-PGPUB	2002/08/20
		and (PCB or (circuit adj board)) and		
		((hot or dry) adj (exhaust or gas or atmosphere))	<u> </u>	
-	27	(pick adj place adj (component or device	USPAT;	2002/08/20
1		or machine)) and (moisture or humidity)	US-PGPUB	18:28
_	13	and (PCB or (circuit adj board)) ("3815251" "4705311" "4769904"	USPAT	2002/08/20
		"4860438" "4951400" "5323528"	OSFAI	09:26
		"5446960" "5449265" "5524765" "5605430" "5613632" "5732478"		
		"5778524").PN.		
-	1	219/\$.ccls. and (pick adj place adj	USPAT;	2002/08/20
		(component or device or machine)) and (moisture or humidity) and (PCB or	US-PGPUB	09:49
		(circuit adj board))		
-	1	6054682.pn. and (pick adj place adj	USPAT;	2002/08/20
		(component or device or machine)) and (moisture or humidity) and (PCB or	US-PGPUB	11:28
		(circuit adj board)) and tray		
_	0	6054682.pn. and (pick adj place adj (component or device or machine)) and	USPAT;	2002/08/20
		(moisture or humidity) and (PCB or	US-PGPUB	11:36
		(circuit adj board)) and tray and bulk		
_	0	6054682.pn. and sensor	USPAT; US-PGPUB	2002/08/20
-	4731	(sensor near (humidity or moisture or	USPAT;	2002/08/20
_	0	(songer near (hymidity on maisty)	US-PGPUB	11:48
		(sensor near (humidity or moisture or vapor)) and (5884392.pn. or 5388945.pn.)	USPAT; US-PGPUB	2002/08/20
-	96	(sensor near (humidity or moisture or	USPAT;	2002/08/20
_	221	vapor)) and (dry adj gas) (sensor near (humidity or moisture or	US-PGPUB USPAT;	11:50
	231	vapor)) and ((hot or dry) adj (delivery	US-PGPUB	2002/08/20 11:51
_	205	or exhaust or gas or atmosphere))		
_	205	(sensor near (humidity or moisture or vapor)) and ((hot or dry) adj (delivery	USPAT; US-PGPUB	2002/08/20 11:52
		or exhaust or gas or atmosphere)) and	OS TGFOB	11.52
_	7	control (sensor near (humidity or moisture or	Hebru	2000/00/00
	'	vapor)) and ((hot or dry) adj (delivery	USPAT; US-PGPUB	2002/08/20 12:13
		or exhaust or gas or atmosphere)) and		1 -5.12
_	33	control and (PCB or (circuit adj board)) (sensor near (humidity or moisture or	USPAT;	2002/08/20
		<pre>vapor)) and (((hot or dry) adj (delivery</pre>	US-PGPUB	12:32
		or exhaust or gas or atmosphere)) with		
_	1	control) (sensor near (humidity or moisture or	USPAT;	2002/08/20
		vapor)) and (((hot or dry) adj (delivery	US-PGPUB	12:33
		or exhaust or gas or atmosphere)) with control) and 5365779.pn.		
_	0	(sensor near (humidity or moisture or	USPAT;	2002/08/20
		vapor)) and (((hot or dry) adj (delivery	US-PGPUB	12:34
		or exhaust or gas or atmosphere)) with control) and 5365779.pn. and (PCB or		
		(circuit adj board))		
-	0	(sensor near (humidity or moisture or	USPAT;	2002/08/20
		<pre>vapor)) and (((hot or dry) adj (delivery or exhaust or gas or atmosphere)) with</pre>	US-PGPUB	12:34
		control) and 5365779.pn. and (wafer or		
		chip or semiconductor or SMD or PCB or (circuit adj board))		
	L	(officate and moutal)		<u> </u>

-	8	(sensor near (humidity or moisture or vapor)) and (((hot or dry) adj (delivery or exhaust or gas or atmosphere)) with control) and (wafer or chip or	USPAT; US-PGPUB	2002/08/20 15:00
		semiconductor or SMD or PCB or (circuit adj board))		
-	11604	(humidity or moisture or vapor) same percentage	USPAT; US-PGPUB	2002/08/20 15:01
-	3533	(remove or removed or removing or dry or dried or drying) same (humidity or moisture or vapor) same percentage	USPAT; US-PGPUB	2002/08/20 15:02
-	834	((remove or removed or removing or dry or dried or drying) with (humidity or moisture or vapor) with percentage)	USPAT; US-PGPUB	2002/08/20 15:04
_	131		USPAT; US-PGPUB	2002/08/20 15:06
-	810	((remove or removed or removing or dry or dried or drying) with (humidity or moisture or vapor) with (percent or percentage)) and (wafer or chip or semiconductor or SMD or PCB or (circuit adj board))	USPAT; US-PGPUB	2002/08/20 15:07
_	325	((remove or removed or removing or dry or dried or drying) with (humidity or moisture or vapor) with (percent or percentage)) and (wafer or (component adj chip) or semiconductor or SMD or PCB or (circuit adj board))	USPAT; US-PGPUB	2002/08/20 15:08
-	333	((eliminate or eliminating or remove or removed or removing or dry or dried or drying) with (humidity or moisture or vapor) with (percent or percentage)) and (wafer or (component adj chip) or semiconductor or SMD or PCB or (circuit adj board))	USPAT; US-PGPUB	2002/08/20 16:26
_	0	(percent or percentage) and 6054682.pn. (percent or percentage) and 5365779.pn.	USPAT; US-PGPUB USPAT;	2002/08/20 15:36 2002/08/20
-	0	(((eliminate or eliminating or remove or removed or removing or dry or dried or drying) adj (humidity or moisture or vapor)) with (percent or percentage)) and (wafer or (component adj chip) or semiconductor or SMD or PCB or (circuit adj board)) and (dry adj (gas or atmosphere))	US-PGPUB USPAT; US-PGPUB	15:36 2002/08/20 16:30
_	46	<pre>(((eliminate or eliminating or remove or removed or removing or dry or dried or drying) adj (humidity or moisture or vapor)) with (percent or percentage)) and (wafer or (component adj chip) or semiconductor or SMD or PCB or (circuit adj board))</pre>	USPAT; US-PGPUB	2002/08/20
_	7	<pre>(((eliminate or eliminating or remove or removed or removing or dry or dried or drying) adj (humidity or moisture or vapor)) with (percent or percentage)) and (dry adj (gas or atmosphere))</pre>	USPAT; US-PGPUB	2002/08/20 16:31
-	1	3809924.pn. and (percent or percentage)	USPAT; US-PGPUB	2002/08/20
_	1	5385882.pn. 5297438.pn.	USPAT; US-PGPUB USPAT;	2002/08/20 18:12 2002/08/20
_	1	5884392.pn.	US-PGPUB USPAT; US-PGPUB	18:12 2002/08/20 18:27

	565	219/385.ccls.	T	
_	363	219/385.CCIS.	USPAT; US-PGPUB	2002/08/20
-	56	1 (USPAT;	2003/01/23
		apparatus or method or process) with	US-PGPUB;	15:03
		(feeding or plac\$3 or mount\$3 or	IBM_TDB	
		install\$3 or assembl\$3 or insert\$3 or put\$4) with (chip or component or IC)		
		with (PCB or (circuit adj board))) and		
		((dry or hot) with (gas or ventilation or	i	
	_	exhhaust)) and (moisture or humidity)		
_	1	5364045.pn. and dry	USPAT;	2003/01/23
			US-PGPUB; IBM TDB	15:04
_	1	5364045.pn. and dry	USPAT;	2003/01/24
			US-PGPUB;	08:47
	1.0	4840400508	IBM_TDB	
-	10	("1848859" "3603528" "3798657" "3920394" "4513862" "5014929"	USPAT	2003/01/24
		"5038934" "5046674" "5123608"		08:47
		"5195689").PN.		
-	2	5364045.URPN.	USPAT	2003/01/24
	_			08:49
-	1	apparatus adj method adj maintaining adj	USPAT;	2003/11/14
		dry adj atmosphere	US-PGPUB; IBM TDB	10:57
-	0	29/\$.ccls. and (apparatus adj maintaining	USPAT;	2003/11/14
		adj dry adj atmosphere)	US-PGPUB;	10:58
			IBM_TDB	
-	14		USPAT;	2003/11/14
		system or machine) same (maintain\$3 or kept or keep\$3 or hold\$3 or conserv\$3)	US-PGPUB; IBM TDB	11:02
		and (dry adj atmosphere) and (IC or chip	1911_100	
		or component)		
-	3	29/\$.ccls. and (apparatus or device or	USPAT;	2003/11/14
	İ	system or machine) same (maintain\$3 or	US-PGPUB;	11:07
		kept or keep\$3 or hold\$3 or conserv\$3) same (dry adj atmosphere) and (IC or chip	IBM_TDB	
		or component)		
-	105	(apparatus or device or system or	USPAT;	2003/11/14
		machine) same (maintain\$3 or kept or	US-PGPUB;	11:08
		keep\$3 or hold\$3 or conserv\$3) same (dry adj atmosphere) and (IC or chip or	IBM_TDB	
		component)		
	10	(apparatus or device or system or	USPAT;	2003/11/14
		machine) same (maintain\$3 or kept or	US-PGPUB;	11:16
		keep\$3 or hold\$3 or conserv\$3) same (dry	IBM_TDB	
		adj atmosphere) same (IC or chip or		
_	20	component) ("4572427" "4704792" "4815913"	USPAT	2003/11/14
		"4838911" "5226713" "5297438"	OSIMI	11:09
j		"5318181" "5364045" "5364225"		
		"5368786" "5371046" "5749234"		
		"5916513" "5944602" "6008476" "6054682" "6105606" "6122918"		
		"6158146" "6357142").PN.		
] -	0	29/729.ccls. and (maintain\$3 or kept or	USPAT;	2003/11/14
		keep\$3 or hold\$3 or conserv\$3) same (dry	US-PGPUB;	11:19
[adj atmosphere) same (IC or chip or	IBM_TDB	
_	0	component) 29/729.ccls. and (maintain\$3 or kept or	ווכסאידי.	2002/11/14
	١	keep\$3 or hold\$3 or conserv\$3) same (dry	USPAT; US-PGPUB;	2003/11/14 11:18
		adj (storage or environment or	IBM TDB	11.10
		atmosphere)) same (IC or chip or		
	_	component)		0000 (0.5./5.)
-	U	29/729.ccls. and (dry adj (storage or environment or atmosphere)) same (IC or	USPAT;	2003/11/14
		chip or component)	US-PGPUB; IBM TDB	11:18
-	0	29/729.ccls. and (dry adj (storage or	USPAT;	2003/11/14
		environment or atmosphere))	US-PGPUB;	11:18
			IBM TDB	

-	53	29/729.ccls. and stor\$4	USPAT;	2003/11/14
1			US-PGPUB;	11:19
			IBM TDB	11:19
_	1	29/729.ccls. and dry same stor\$4	· —	2002/22/24
	1	237723.0013. and dry same scors4	USPAT;	2003/11/14
			US-PGPUB;	11:19
Í _	1	(34/380,218).ccls. and (maintain\$3 or	IBM_TDB	
	1	kept or keep\$3 or hold\$3 or conserv\$3)	USPAT;	2003/11/14
		same (dry adj atmosphere) same (IC or	US-PGPUB;	11:20
		chip or component)	IBM_TDB	
_	0			
_		(LLI) TOULD, IT, COLD. and (maintains) Of	USPAT;	2003/11/14
		kept or keep\$3 or hold\$3 or conserv\$3)	US-PGPUB;	11:21
		same (dry adj atmosphere) same (IC or	IBM_TDB	
		chip or component)		
_	0	((DDI) DONA, (I) COID: WING (WIY EG)	USPAT;	2003/11/14
		atmosphere)	US-PGPUB;	11:21
			IBM_TDB	
-	0	(221/150A,71).ccls. and (dry adj stor\$4)	USPAT;	2003/11/14
			US-PGPUB;	11:21
			IBM TDB	
-	270	(221/150A,71).ccls.	USPAT;	2003/11/14
	i		US-PGPUB;	11:21
			IBM TDB	
_	126	(221/150A,71).ccls. and stor\$3	USPAT;	2003/11/14
			US-PGPUB;	11:22
			IBM TDB	11.02
-	72	(221/150A,71).ccls. and stor\$3 and	USPAT;	2003/11/14
		(component or IC or chip)	US-PGPUB;	11:22
	1		IBM TDB	11.22
-	16	(221/150A,71).ccls. and stor\$3 with	USPAT;	2003/11/14
		(component or IC or chip)	US-PGPUB;	11:22
		(IBM TDB	11.22
_	1	6054682.URPN.	USPAT	2002/11/14
	1	000 1002 . VIII IV.	USPAT	2003/11/14
_	13	("3815251" "4705311" "4769904"	HCDAM	11:23
	13	"4860438" "4951400" "5323528"	USPAT	2003/11/14
				11:23
		, , , , , , , , , , , , , , , , , , , ,		
		"5605430" "5613632" "5732478"		
	ll	"5778524").PN.		